

NOTES:

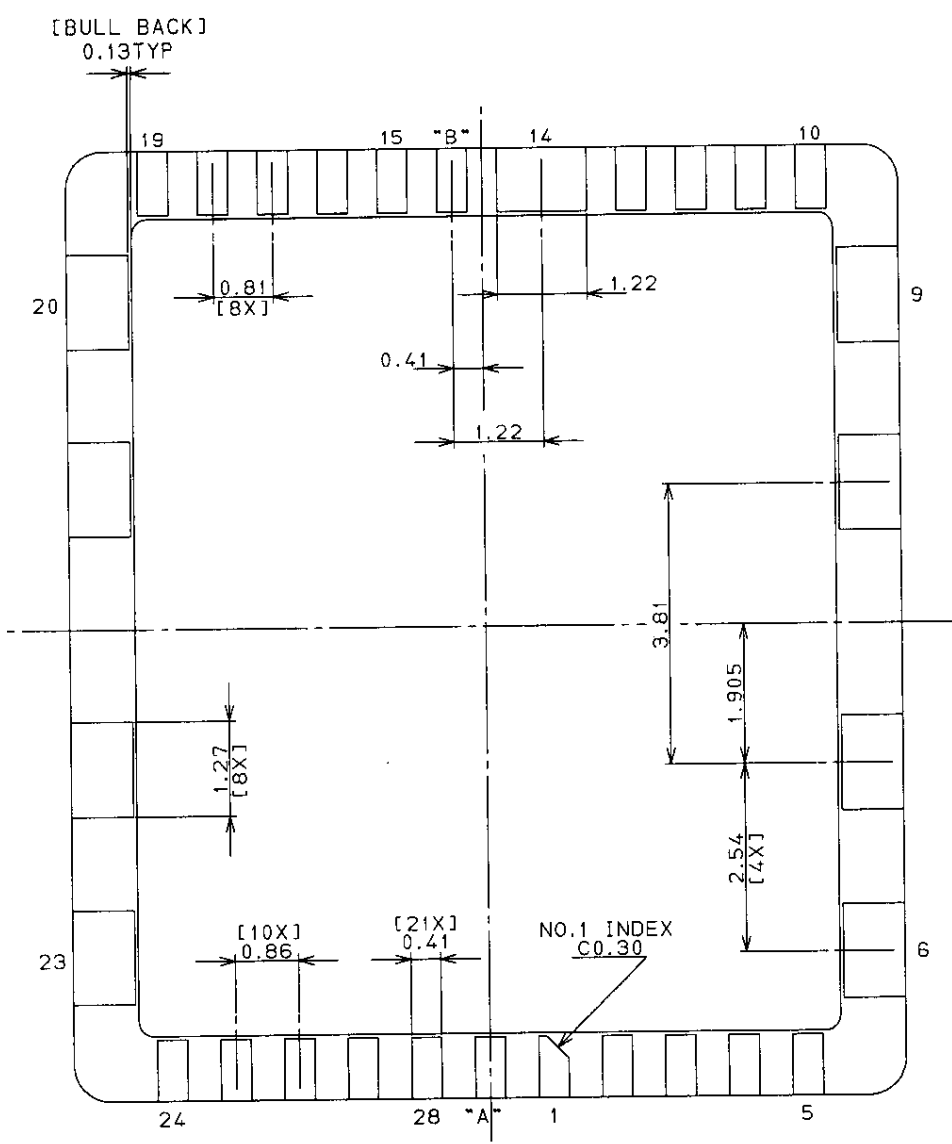
1. GOLD PLATE 1.52μm MIN OVER 1.27~8.89μm NICKEL.
2. LEAD RESISTANCE ----- 500mΩ MAX
3. SEAL RING ISOLATED.
4. PAD "A" AND "B" TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. DIE ATTACH PAD ARE FLOATING FROM ANY OUTER PINS.

MODIFIED DWG NO. IPK28F1-8476D

3	STAND OFF PIN	ALLOY42		B	RE DRAWING	MAY-31-2004
2	PIN	ALLOY42		A	RE DRAWING	MAY-20-2004
1	CERAMIC	BLACK ALUMINA		φ	NEW DRAWING	MAY-14-2004
Item	Name	Material	Description	Rev.	Description	Date
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1%			DRAWN	T. OKUMURA	NTK	
N. L. T. 1 DECIMALS X. X. ± 0.25 2 DECIMALS X. XX ± 0.13			CHECKED	N. NAKAYAMA	NGK SPARK PLUG CO., LTD.	
CUSTOMER			APPROVED	T. NOMURA	TITLE	
DWG NO.			UNIT	MM	DWG NO.	
			SCALE	/	IPK28F1-8476E	



B SEE SHEET 1 OF 2



B/G PADS DETAIL

Rev.	Description	Date
B	RE DRAWING	MAY-31-2004
A	RE DRAWING	MAY-20-2004
φ	NEW DRAWING	MAY-14-2004

UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1 % N. L. T. 1 DECIMALS X, Y ± 0.25 2 DECIMALS X, X ± 0.13		DRAWN T. OKUMURA	NTTK NGK SPARK PLUG CO., LTD. TITLE
CUSTOMER		CHECKED N. NAKAYAMA	
DWG NO.		APPROVED T. NOMURA	B/G PADS DETAIL
		UNIT MM	DWG NO.
		SCALE /	IPK28F1-8476E

MODIFIED DWG NO. IPK28F1-8476D